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Final Product Change Notification   201506014F01

Issue Date: 19-Jun-2015
Effective Date: 05-Oct-2015

Here's your personalized quality information concerning products Digi-Key purchased from NXP.
For detailed information we invite you to view this notification online

QUALITY

Change Category

[ ] Wafer Fab process	[ ] Assembly Process	[ ] Product Marking	[ ] Design
[ ] Wafer Fab materials	[X] Assembly Materials	[ ] Electrical spec./Test coverage	[ ] Mechanical Specification
[ ] Wafer Fab location	[ ] Assembly Location	[ ] Test Location	[ ] Packing/Shipping/Labeling

Conversion of CLIP from CD3 to CD4 Dual Dimple Post Clip for a subset of LFPAK Types

Details of this Change

NXP intend to implement a change of the LFPAK top clip from CD3 to CD4 DD (Dual Dimple Post Design)
Why do we Implement this Change
This change is being implemented as a quality improvement to the product. The CD4 DD LFPAK clip guarantees less tilt of the clip and better solder thickness uniformity under the dimples.
Identification of Affected Products
Product identification does not change

Product Availability

Sample Information
Samples are available upon request
Production
Planned first shipment 05-Oct-2015

Impact

no impact to the product's functionality anticipated.
Data Sheet Revision
No impact to existing datasheet
Disposition of Old Products
Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 19-Jul-2015.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:
e-mail address   powermos.pcn@nxp.com
At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

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